

Description

The IRLR3105TRPBF uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 60V I_{D} = 20 A$

 $R_{DS(ON)}$ < 32m Ω @ V_{GS} =10V

Application

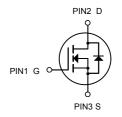
Battery protection

Load switch

Uninterruptible power supply

D S

TO-252-2L (DPAK)



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
IRLR3105TRPBF	TO-252-2L(DPAK)	HXY MOSFET	2500

Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units	
Vps	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	I _D @T _C =25°C Continuous Drain Current, V _{GS} @ 10V¹		А	
I _D @T _C =100°C Continuous Drain Current, V _{GS} @ 10V ¹		10	А	
Іом	Pulsed Drain Current ²	80	А	
EAS	Single Pulse Avalanche Energy ³	38	mJ	
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
Tu	Operating Junction Temperature Range	-55 to 150	°C	



Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics		1		L	l		
Drain-Source Breakdown Vo	oltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA		-	-	V
Gate-Body Leakage Current		Igss	V _{DS} = 0V, V _{GS} = ±20V		-	±100	nA
Zero Gate Voltage Drain	T _J =25°C		.,	-	-	1	μА
Current	T _J =100°C	IDSS	$V_{DS} = 60V$, $V_{GS} = 0V$	-	-	100	
Gate-Threshold Voltage	•	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.7	2.5	٧
			V _{GS} = 10V, I _D = 10A	V _{GS} = 10V, I _D = 10A -		32	
Drain-Source on-Resistance) ⁴	R _{DS(on)}	V _{GS} = 4.5V, I _D = 5A	-	31.5	40	mΩ
Forward Transconductance	ı	g fs	V _{DS} = 5V, I _D = 10A	-	15.5	_	S
Dynamic Characteristic	s ⁵		1		l	I	
Input Capacitance		C _{iss}		-	1355	-	
Output Capacitance Reverse Transfer Capacitance Gate Resistance		Coss	V _{DS} = 30V, V _{GS} =0V, f =1MHz	-	60	-	pF
		C _{rss}		-	49	-	
		R _G	f=1MHz	-	1.2	-	Ω
Switching Characteristi	CS ⁵	4				ı	
Total Gate Charge		Qg		-	22	-	
Gate-Source Charge Gate-Drain Charge		Q_{gs}	$V_{GS} = 10V, V_{DD} = 30V,$ $I_{D} = 10A$	-	4.2	-	nC
		Q_{gd}		-	6.9	-	
Turn-on Delay Time		t _{d(on)}		-	6.4	-	
Rise Time		t _r	$V_{GS} = 10V, V_{DD} = 30V,$	-	15.3	_	ns
Turn-off Delay Time		t _{d(off)}	$R_G = 3\Omega$, $I_D = 10A$	-	25	_	
Fall Time		t _f		-	7.6	_	
Body Diode Reverse Recovery Time Body Diode Reverse Recovery Charge		trr		-	26	_	ns
		Qrr	- I _F =10A, dI _F /dt=100A/μs	-	45	-	nC
Drain-Source Body Dio	de Charactei	ristics		L	ı	ı	
Diode Forward Voltage⁴		V _{SD}	I _S = 10A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current T _C =25°C		Is	-	-	-	20	Α

^{1.} Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C
2. The EAS data shows Max. rating . The test condition is V_{DD}=25V, V_{GS}=10V, L=0.4mH, I_{AS}=14A
3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.

5. This value is guaranteed by design hence it is not in cluded in the production test.



Typical Characteristics

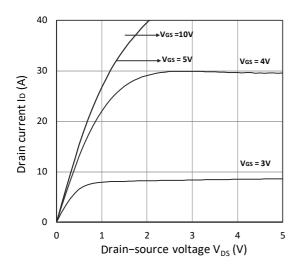


Figure 1. Output Characteristics

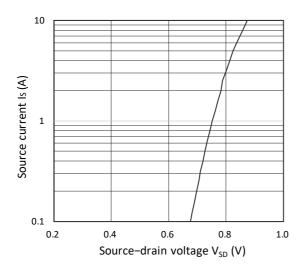


Figure 3. Forward Characteristics of Reverse

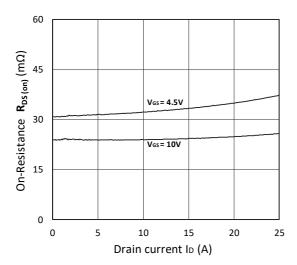


Figure 5. $R_{DS(ON)}$ vs. I_D

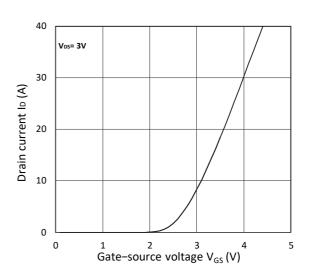


Figure 2. Transfer Characteristics

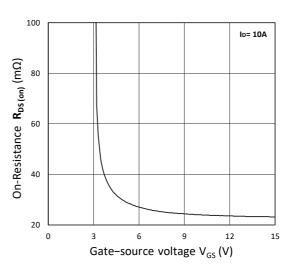


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

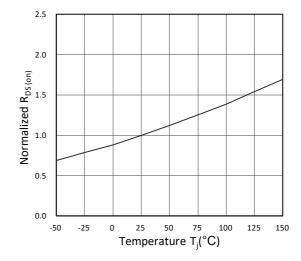
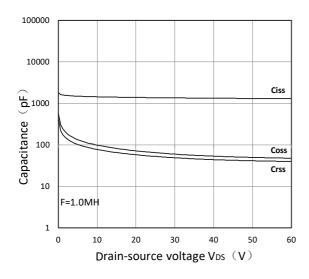


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



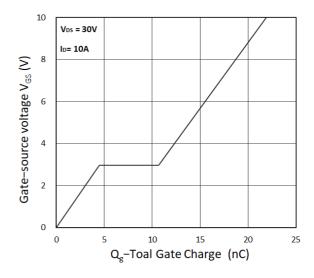
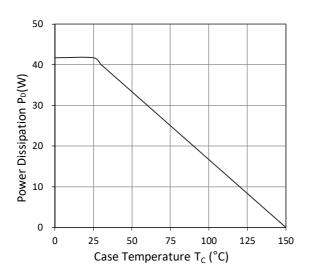


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics



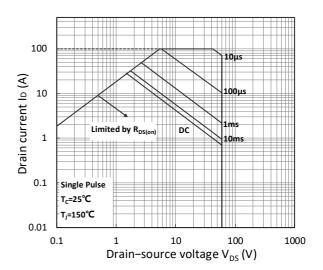


Figure 9. Power Dissipation

Figure 10. Safe Operating Area

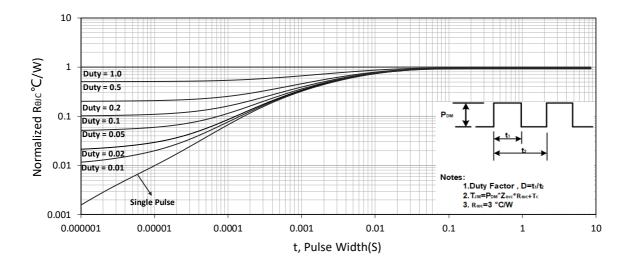
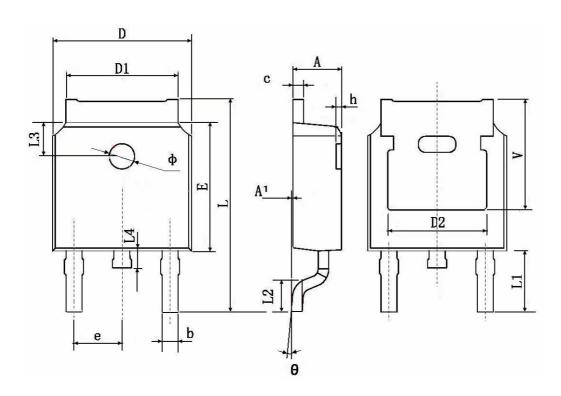


Figure 11. Normalized Maximum Transient Thermal Impedance

TO-252-2L(DPAK) Package Information



Complete	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production.

 HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.